A TDK Group Company

SSI 32R2300/2300R/2301/2301R +3.3V/5.0V, 2, 4-Channel

2-Terminal Read/Write Device

Advance Information

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DESCRIPTION

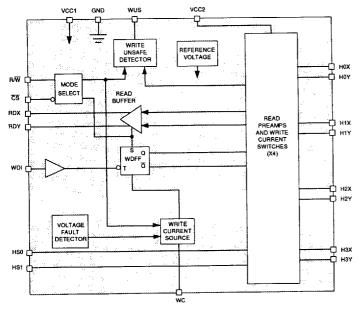
The SSI 32R2300/2300R are BiCMOS monolithic integrated circuits designed for use with two-terminal recording heads. They provide a low noise read amplifier, write current control, and data protection circuitry for up to four channels. The SSI 2300R option provides internal 350Ω damping resistors. Damping resistors are switched in during Write mode and switched out during Read mode. The SSI 32R2300 option does not provide a damping resistor. Power supply fault protection is provided by disabling the write current generator during power sequencing. System write to read recovery time is significantly improved by making the read channel outputs high impedance.

The SSI 32R2300/2300R require only a +3.3V power supply and are available in a variety of packages. They are hardware compatible with the SSI 32R4610A and SSI 32R2020R Read/Write devices. The SSI 32R2301/2301R is identical to the SSI 32R2300/2300R, but comes in 24-pin package.

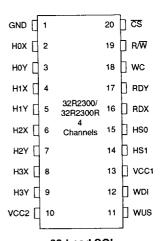
FEATURES

- +3.0V 5.5V voltage supply
- Low power
 - PD = 63 mW read mode (Nom) (@3.3V supply)
 - PD = 1 mW idle (Max)
- High Performance:
 - Read mode gain = 200 V/V
 - Input noise = 0.50 nV/√Hz (Nom)
 - input capacitance = 9 pF (Nom)
 - Write current range = 3-25 mA
- Self switching damping resistance
- Pin compatible with the SSI 32R4610AR and SSI 32R2020R
- · Write unsafe detection
- Power supply fault protection

BLOCK DIAGRAM



PIN DIAGRAM



20-Lead SOL

CAUTION: Use handling procedures necessary for a static sensitive component. SSI 32R2300/2300R/2301/2301R

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CIRCUIT OPERATION

The SSI 32R2300/2300R have the ability to address up to 4 two-terminal heads and provide write drive or read amplification. Mode control and head selection are described in Tables 1 and 2. The TTL inputs R/W, CS, HS0 and HS1 have internal pull-up resistors.

TABLE 1: Mode Select

C S	R/W	Mode
0	0	Write
0	1	Read
1	0	Idle
1	1	ldle

TABLE 2: Head Select

HS1	HS0	Head
0	0	0
0	1	1
1	0	2
1	1	3

PIN DESCRIPTIONS

NAME	TYPE	DESCRIPTION		
HS0, HS1 +	ı	Head Select: selects one of four heads		
CS	l l	Chip Select: a high inhibits the chip		
R/ W +	<u> </u>	Read/Write : a high selects Read mode		
wus +	0	Write Unsafe: a high indicates an unsafe writing condition		
WDI †	-	Write Data In: a negative transition on WDI changes the direction of the current in the recording head		
H0X - H3X; H0Y - H3Y	1/0	X, Y Head Connections		
RDX, RDY +	0	X, Y Read Data: differential read data output		
wc	Write Current: used to set the magnitude of the write current			
VCC1 I		Power Supply		
VCC2		Power Supply for Write current drivers		
GND	1	Ground		

[†] When more that one R/W device is used, signals can be wire OR'ed

WRITE MODE

Taking both \overline{CS} and R/ \overline{W} low selects write mode which configures the SSI32R2300/2300R as a current switch and activates the Write Unsafe (WUS) detector circuitry. Head current is toggled between the X and Y side of the selected head on each high to low transition of the Write Data Input (WDI). Note that a preceding Read to Write transition or Idle to Write transition initializes the Write Data Flip-Flop to pass write current into the "X" side of the device. In this case, the Y side is higher potential than the X side. The magnitude of the write current (0-pk) is given by:

$$Iw = Aw \cdot \frac{Vwc}{Rwc} = \frac{K}{Rwc}$$

where Aw is the write current gain. RWC is connected from pin WC to GND. Note the actual head current lx, y is given by:

$$lx, y = \frac{lw}{1 + Rh/Rd}$$

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Where:

Rh = Head resistance plus external wire resistance

Rd = Damping resistance

In Write mode a 350 Ω damping resistor is switched in across the Hx, Hy ports (32R2300R only).

VOLTAGE FAULT

A voltage Fault detection circuit improves data security by disabling the write current generator during a voltage fault or power startup in Read or Write mode.

WRITE UNSAFE

Any of the following conditions will be indicated as a high level on the Write Unsafe, WUS, open collector output.

- WDI frequency too low
- Device in Read mode
- Device not selected
- No head current
- Open head
- Head short to ground

WUS is valid in the write current/head characteristic region defined by $5 < lh \cdot Lh < 50 \text{ mA} \cdot \mu H$, and 1 < Rh< 1.25/lh. After the fault condition is removed, two negative transitions on WDI are required to clear WUS. Overcurrent protection during a head short to ground is accomplished by placing a series resistor between VCC1 and VCC2. The write current driver will shut down when VCC1 - VCC2≥0.3V. The resistor must be sized so that VCC1 - VCC2 ≤ 0.15V in normal operation.

READ MODE

The Read mode configures the SSI 32R2300/2300R as a low noise differential amplifier and deactivates the write current generator. The damping resistor is switched out of the circuit allowing a high impedance input to the read amplifier. The RDX and RDY output are driven by emitter followers. They should be AC coupled to the load. The HnX, HnY inputs are noninverting to the RDX, RDY outputs.

Note that in Idle or Write mode, the read amplifier is deactivated and RDX, RDY outputs become high impedance. This facilitates multiple R/W applications (wired-OR RDX, RDY) and minimizes voltage change when switching from Write to Read mode. Note also that the write current source is deactivated for both the Read and Idle mode.

IDLE MODE

Taking CS high selects the Idle mode which switches the RDX and RDY outputs into a high impedance state and deactivates the device. Power consumption in this mode is held to a minimum.

ELECTRICAL SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS

Operation above maximum ratings may permanently damage the device.

PARAMETER		RATING
DC Supply Voltage	VCC1	-0.3 to +6 VDC
	VCC2	-0.3 to +6 VDC
Write Current	lw	30 mA
Digital Input Voltage	Vin	-0.3 to VCC1 +0.3 VDC
Head Port Voltage	VH	-0.3 to VCC2 +0.3 VDC
Output Current: RDX, RDY	10	-10 mA
<u></u>	WUS	+8 mA
Storage Temperature	Tstg	-55 to +150°C

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RECOMMENDED OPERATING CONDITIONS

PARAMETER	RATING
DC Supply Voltage VCC1 = VCC2	3.3 ±10%, 5.0 ±10% VDC
Recommended Head Load Range Lh	0.3 - 5.0 μΗ
WUS Operating Range lw • Lh	5.0 - 50.0 mA • μH
Head Differential Load Capacitance	25 pF max
Ambient Operating Temperature	0 - 70 °C

DC CHARACTERISTICS

Recommended operating conditions apply unless otherwise specified.

PARAMETER	CONDITIONS	MIN	МОМ	MAX	UNIT
VCC1 Supply Current	Read Mode Vcc = 3.3V ±10%		19	29	mA
	Write Mode Vcc = 3.3V ±10%		2 + 0.2 lw	3 + 0.3 lw	mA
	Idle Mode Vcc = 3.3V ±10%		0.15	0.27	mA
VCC2 Supply Current	Read Mode Vcc = 3.3V ±10%		-	0.1	mA
	Write Mode Vcc = 3.3V ±10%		1.0 + lw	3.0 + lw	mA
	Idle Mode Vcc = 3.3V ±10%		-	0.01	mA
Power Dissipation	Read Mode Vcc = 3.3V ±10%		63	105	mW
	Write Mode Vcc = 3.3V ±10%		10 + 4 • lw	20 + 5 • lw	mW
	Idle Mode Vcc = 3.3V ±10%		0.5	1	mW
VCC1 Supply Current	Read Mode Vcc = 5.0V ±10%		20	32	mA
	Write Mode Vcc = 5.0V ±10%		3 + 0.2 lw	5 + 0.3 lw	mA
	Idle Mode Vcc = 5.0V ±10%		0.25	0.45	mA
VCC2 Supply Current	Read Mode Vcc = 5.0V ±10%			0.1	mA
	Write Mode Vcc = 5.0V ±10%		1.0 + lw	3.0 + lw	mA
	Idle Mode Vcc = 5.0V ±10%			0.01	mA
Power Dissipation	Read Mode Vcc = 5.0V ±10%		100	180	mW
	Write Mode Vcc = 5.0V ±10%		20 + 6 • lw	45 + 7.2 lw	mW
	Idle Mode Vcc = 5.0V ±10%		1.25	2.5	mW

DIGITAL INPUTS

Input Low voltage (VIL)					0.8	VDC
Input High Voltage (VIH)			2.0			VDC
Input Low Current	VIL = 0.4	VCC = 3.6V VCC = 5.5V	-0.4 -0.4	09 -0.13		mA mA
Input High Current	VIH = 2.7V			0	20	μА
WUS Output Low Voltage (VOL)	lol = 2 mA ma	ıx		.35	0.5	VDC

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WRITE CHARACTERISTICS

Recommended operating conditions apply unless otherwise specified.

PARAMETER	CONDITIONS		MIN	NOM	MAX	UNIT
VCC1 Fault Voltage	lw < 0.2 mA			2.5	2.75	VDC
Write Current Gain (Aw)	lw = 3 mA to 20 mA		18.4	20	21.6	mA/mA
Write Current Gain (Aw)	lw = 20 mA to 25 mA		17.0	20	23	mA/mA
Write Current Voltage (VWC)			1.2	1.3	1.4	V
Differential Head Voltage Swing	Open head		4.0	4.8		Vpp
Unselected Head Current	lw ≥ 10 mA				0.02 lw	mA (pk)
	lw < 10 mA				0.2	mA (pk)
Head Differential Load	32	R2300	2400	3000	3600	Ω
Resistance (Rd)	32F	2300R	250	350	450	Ω
WDI Pulse Width	Vil ≤ 0.8V, Vih ≥ 2.0V	PWH	5			ns
	$t_i = t_r = 1$ ns	PWL	10			ns
Write Current Range (lw)			3		25	mA

READ CHARACTERISTICS

Recommended operating conditions apply unless otherwise specified. CL (RDX, RDY) < 20 pF, RL (RDX, RDY) = 1 k Ω .

Differential Voltage	Gain	Vin = 1 mVpp @1 MHz	160	200	240	V/V
Voltage BW -1dB		$ Zs < 5\Omega$, Vin = 1 mVpp	20	35		MHz
	-3dB		40	70		MHz
Input Noise Voltage		BW = 15 MHz, Lh = 0, Rh = 0		0.50	0.75	nV/√Hz
Input Noise Current				3		pA/√Hz
Differential Input Ca	pacitance	Vin = 1 mVpp, f = 5 MHz		9	14	pF
Differential Input Re	sistance	Vin = 1 mVpp, f = 5 MHz				
•		32R2300	500	750	1800	Ω
		32R2300R	500	750	1800	Ω
Dynamic Range		AC input voltage where gain falls to 90% of its small signal gain value, f = 5 MHz	2	5		mVpp
Common Mode Rejection Ratio		Vin = 0 VDC + 100 mVpp @ 5 MHz	45	60		dΒ
Power Supply Reject	tion Ratio	100 mVpp @ 5 MHz on VCC	40	70		dB
Channel Separation		Unselected channels driven with Vin = 0 VDC + 100 mVpp	45	60		dB
Output Offset Voltag	ge		-200		+200	m∨
Single Ended Output Resistance		f = 5 MHz		60	100	Ω
Output Current		AC coupled load, RDX to RDY	1.0	2.0		mA
RDX, RDY Common	n Mode		Vcc-1.0	V∞-1.35	Vcc-1.70	VDC

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SWITCHING CHARACTERISTICS

Recommended operating conditions apply unless otherwise specified. IW = 15 mA, Lh = 1.0 μ H, Rh = 30 Ω f(Data) = 5 MHz.

PARAMETER		CONDITIONS	MIN	NOM	MAX	UNIT
R/W	Read to Write	R/W to 90% of write current		0.3	1.0	μs
	Write to Read	R/W to 90% of 100 mV Read signal envelope		0.4	1	μs
CS	Unselect to Select	CS to 90% of 100 mV 10 MHz Read signal envelope		0.6	2	μs
	Select to Unselect	CS to 10% of write current		0.1	1	μs
HS0,1	to any Head	To 90% of 100 mV 10 MHz Read signal envelope		0.2	1	μs
WUS*	Safe to Unsafe (TD1)	Write mode, loss of WDI transitions; Defines max WDI period for WUS operation	0.6	2.0	3.6	μs
	Unsafe to Safe (TD2)	Fault cleared: from second negative WDI transition		0.2	1.0	μs
WDI	Frequency Range	Valid WUS	1.67		25	MHz
Head (Current	Lh = 0, Rh = 0				
	WDI to Ix - Iy (TD3)	from 50% points		25	40	ns
	Asymmetry	WDI has 1 ns rise/fall time			1.5	ns
	Rise/fall Time	10% to 90% points				
		lw = 15 mA, Rh = 0, Lh = 0		6	9	ns
		lw = 15 mA, $Rh = 30Ω$, $Lh = 1μH$		14	18	ns

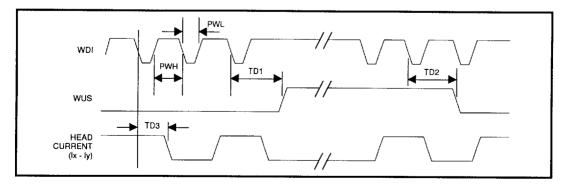


FIGURE 1: Write Mode Timing Diagram

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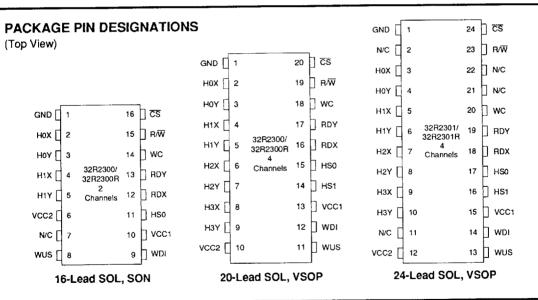
Worst Case Read Input Noise Voltage vs. Input Impedance for SSI 32R2300R

Case 1: IC Base sheet resistance = Maximum Hence, IC bias current = Minimum

	Tj = 25°C	Tj = 110°C	Units
Vn (Max)	TBD	TBD	nV∕√Hz
Rin (Min)	TBD	TBD	Ω
Cin (Max)	TBD	TBD	pF

Case 2: IC Base sheet resistance = Minimum
Hence, IC bias current = Maximum

<u> </u>	Tj = 25°C	Tj = 110°C	Units
Vn (Max)	TBD	TBD	nV√Hz
Rin (Min)	TBD	TBD	Ω
Cin (Max)	TBD	TBD	pF



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